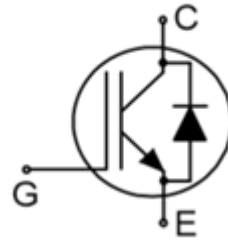


## Trench Field-Stop Technology IGBT

### Features

- 650V, 75A
- $V_{CE(sat)(typ.)} = 1.65V @ V_{GE}=15V, I_C=75A$
- Low Switching Losses
- $V_{CE(sat)}$  with Positive Temperature Coefficient
- Pb-free Lead Plating; RoHS Compliant



### Applications

- Charging pile
- Uninterrupted Power Supply
- Solar converters
- Motor Drives

Order codes	$V_{CE}$	$I_C$	$V_{CEsat}, T_{vj}=25^{\circ}C$	$T_{vjmax}$	Marking	Package
XD075Q065AY1S3	650V	75A	1.65V	175 $^{\circ}C$	D75Q65AY1	TO247-3

### Absolute Maximum Ratings

Symbol	Parameter	Value	Unit
$V_{CES}$	Collector-Emitter Voltage	650	V
$V_{GES}$	Gate-Emitter Voltage	$\pm 20$	V
$I_C$	Continuous Collector Current ( $T_C=25^{\circ}C$ )	150	A
	Continuous Collector Current ( $T_C=100^{\circ}C$ )	75	A
$I_F$	Diode Continuous Forward Current ( $T_C=25^{\circ}C$ )	100	A
	Diode Continuous Forward Current ( $T_C=100^{\circ}C$ )	75	A
$I_{FM}$	Diode Maximum Forward Current (Note 1)	300	A
$P_D$	Maximum Power Dissipation ( $T_C=25^{\circ}C$ )	625	W
$T_J$	Operating Junction Temperature Range	-40 to 175	$^{\circ}C$
$T_{STG}$	Storage Temperature Range	-55 to 175	$^{\circ}C$

### Thermal Data

Symbol	Parameter	Max.	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case for IGBT	0.24	$^{\circ}C/W$

**Electrical Characteristics** ( $T_c=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{CES}$	Collector-Emitter Breakdown Voltage	$V_{GE}=0V, I_C=250\mu A$	650	---	---	V
$I_{CES}$	Collector-Emitter Leakage Current	$V_{CE}=650V, V_{GE}=0V$	---	---	80	$\mu A$
$I_{GES}$	Gate Leakage Current, Forward	$V_{GE}=20V, V_{CE}=0V$	---	---	200	nA
	Gate Leakage Current, Reverse	$V_{GE}=-20V, V_{CE}=0V$	---	---	-200	nA
$V_{GE(th)}$	Gate Threshold Voltage	$V_{GE}=V_{CE}, I_C=250\mu A$	3.5	---	6.0	V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$V_{GE}=15V, I_C=75A$	---	1.65	2.1	V
$t_{d(on)}$	Turn-on Delay Time	$V_{CC}=400V$ $V_{GE}=\pm 15V$ $I_C=75A$ $R_G=5\Omega$ Inductive Load $T_c=25^\circ\text{C}$	---	26	---	ns
$t_r$	Turn-on Rise Time		---	120	---	ns
$t_{d(off)}$	Turn-off Delay Time		---	94	---	ns
$t_f$	Turn-off Fall Time		---	78	---	ns
$E_{on}$	Turn-on Switching Loss		---	2.7	---	mJ
$E_{off}$	Turn-off Switching Loss		---	1.6	---	mJ
$C_{ies}$	Input Capacitance		$V_{CE}=25V$	---	2643	---
$C_{oes}$	Output Capacitance	$V_{GE}=0V$	---	325	---	pF
$C_{res}$	Reverse Transfer Capacitance	$f=1\text{MHz}$	---	58	---	pF

**Diode Characteristics** ( $T_c=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$V_F$	Diode Forward Voltage	$I_F=75A$	---	2.0	2.6	V
$t_{rr}$	Diode Reverse Recovery Time	$V_R=200V$ $I_F=75A$ $V_{GE}=0V$	---	49	---	ns
$I_{rr}$	Diode Peak Reverse Recovery Current		---	4.3	---	A
$Q_{rr}$	Diode Reverse Recovery Charge		---	121	---	nC

Note 1: Repetitive Rating: Pulse width limited by maximum junction temperature

## Typical Characteristics

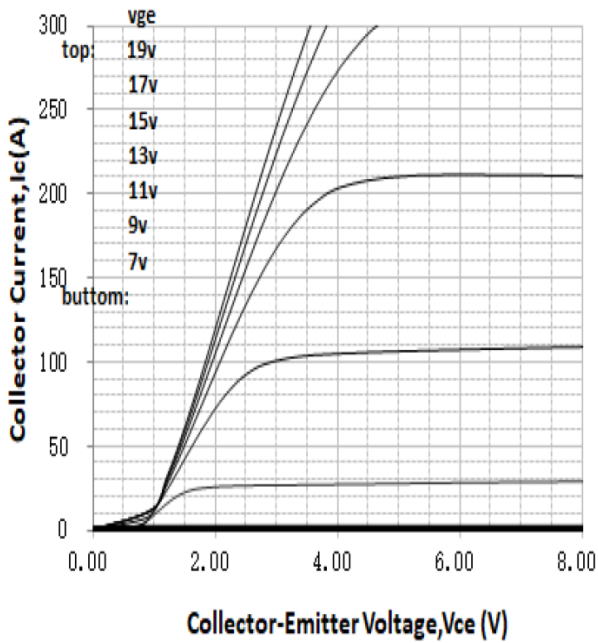


Fig. 1 Typical IGBT Output Characteristics at  $T_J=25^\circ\text{C}$

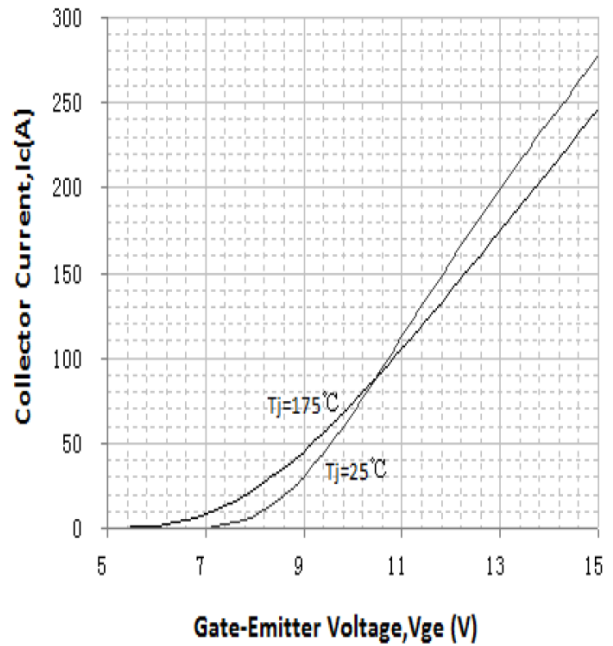


Fig. 2 Typical Transfer Characteristics

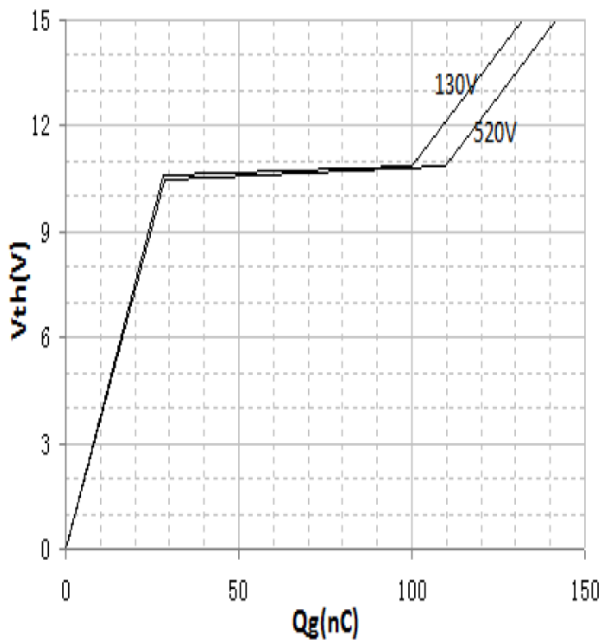


Fig. 3 Gate charge characteristics

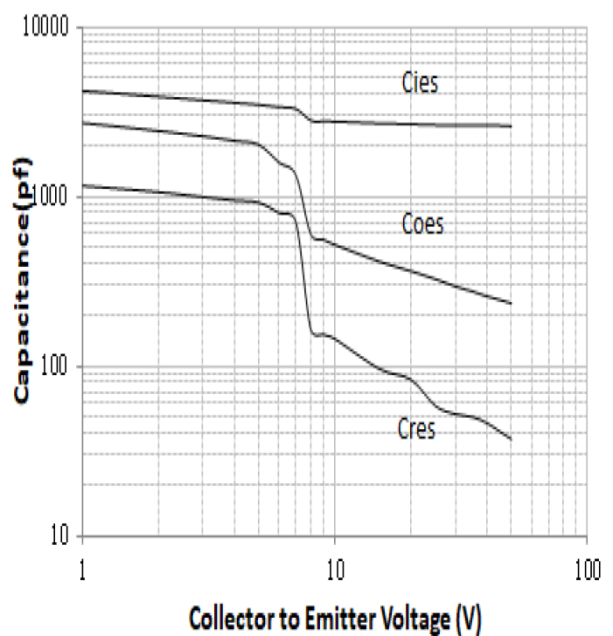


Fig. 4 Capacitance characteristics

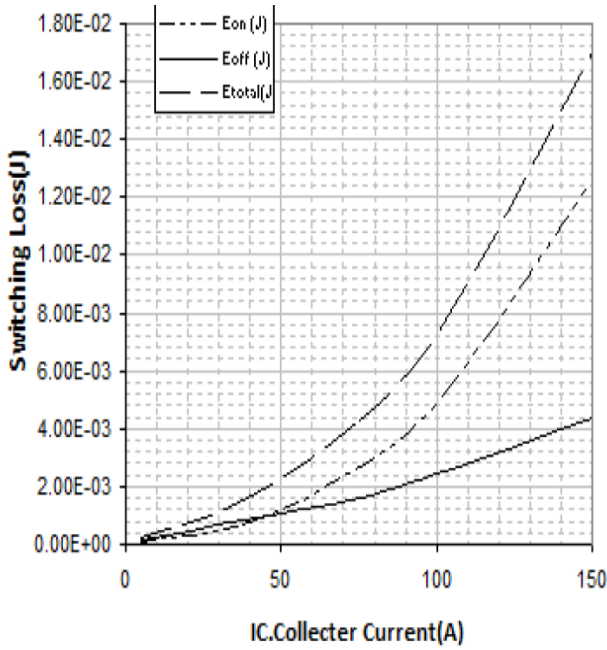


Fig. 5 Typical Energy Loss vs.  $I_c$  at  $T_c=25^\circ\text{C}$ ,  $V_{CE}=400\text{V}$ ,  $V_{GE}=15\text{V}$ ,  $R_g=5\ \Omega$

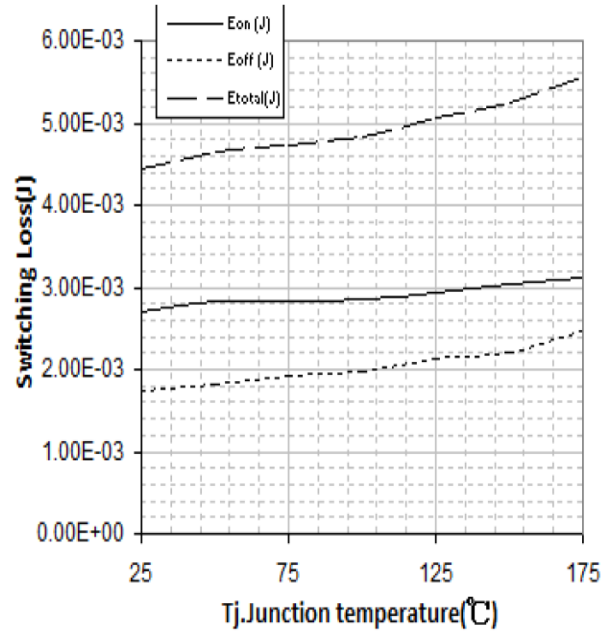


Fig. 6 Typical Switching Time vs.  $T_j$  at  $V_{CE}=400\text{V}$ ,  $V_{GE}=15\text{V}$ ,  $I_c=75\text{A}$ ,  $R_g=5\ \Omega$

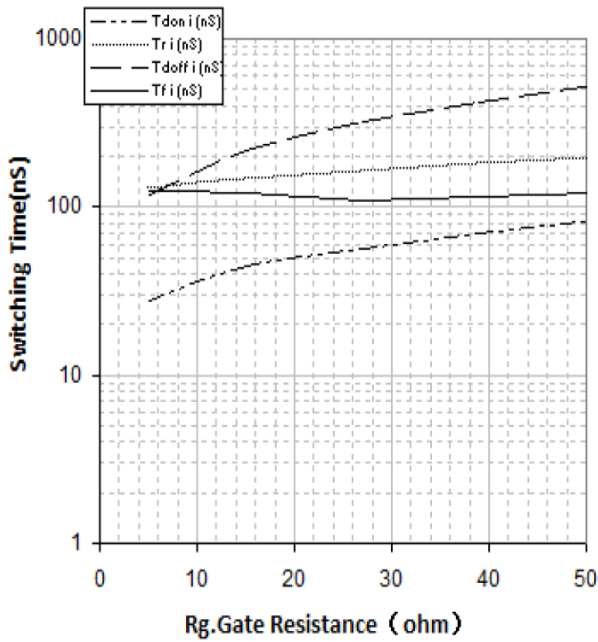


Fig. 7 Switching times vs. gate current

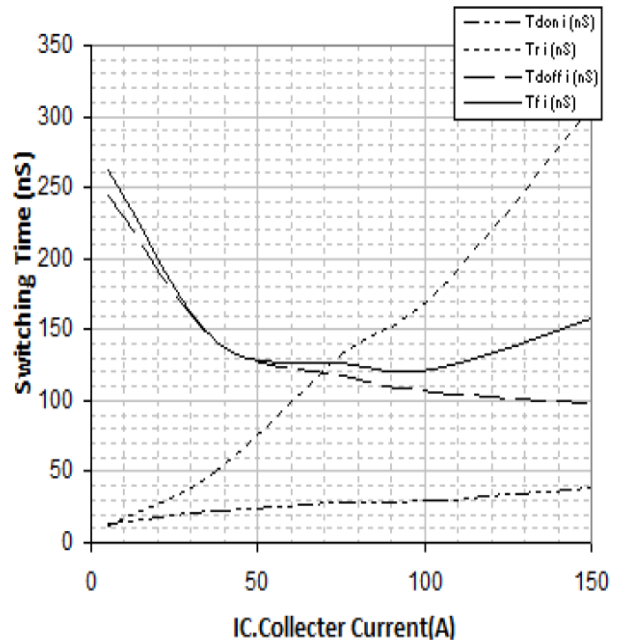
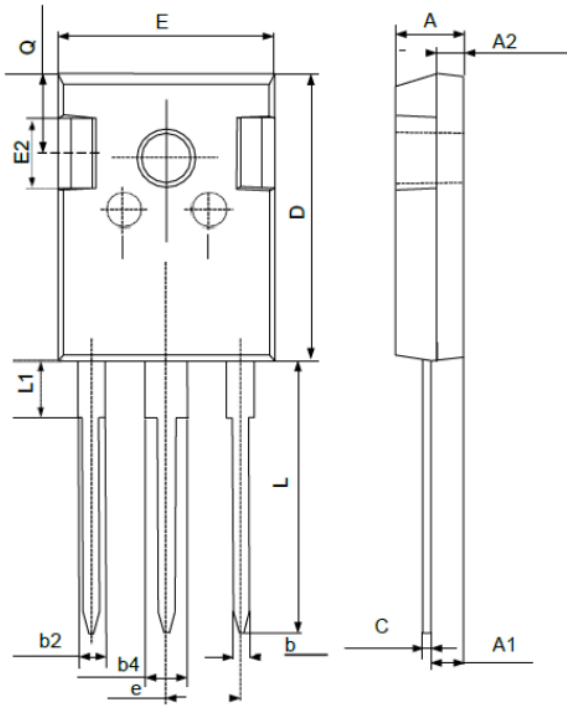


Fig. 8 Switching times vs. collector current

# Package Information

TO-247



SYMBOL	MIN	NOM	MAX
A	4.80	5.00	5.20
A1	2.21	2.41	2.59
A2	1.85	2.00	2.15
b	1.11	----	1.36
b2	1.91	----	2.25
b4	2.91	----	3.25
c	0.51	----	0.75
D	20.80	21.00	21.30
E	15.50	15.80	16.10
E2	4.40	5.00	5.20
e	5.44 BSC		
L	19.72	19.92	20.22
L1	----	----	4.30
Q	5.60	5.80	6.00